RF/DC sputtering and e-beam evaporation

Manufacturer: Leybold
Model: UNIVEX900

General Description:
The UNIVEX900 is an advanced coating system which can perform co-sputtering and e-beam evaporation in the same chamber. This tool is compatible with 8-inch wafers (200 mm) and can be used to deposit many materials such as metals, oxides or nitrides.

Key Specifications:

- **Sputtering**
  - Max. thickness 3 µm
  - RF and DC sputtering
  - Co-sputtering possible
  - Reactive sputtering with O₂ and/or N₂
  - Conformal coatings
  - Target size 4”
  - Max. temperature substrate 400 °C
  - Materials: SiO₂, Si dopped, Al, Mo, AlN, Cu, Ag, Ti, Cr, Ni, PZT, Si (undoped), SiₙNₘ, Ta₂O₅, Al₂O₃, SiC,…

- **E-beam evaporation**
  - Max. thickness 400 nm
  - High deposition rate
  - Lowest pressure achievable ~10⁻⁷ mbar
  - Materials: Ag, Al, Au, Cr, Pt, Ti, Ni
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<thead>
<tr>
<th><strong>Availability</strong></th>
<th>Use allowed for all researchers with permission</th>
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<tbody>
<tr>
<td><strong>Location</strong></td>
<td>Cleanroom C5</td>
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<td>Europastraße 12</td>
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<td>9524 Villach</td>
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